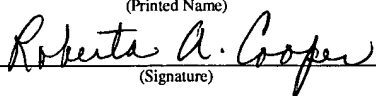




IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paton et al.  
Title: OFFSET SPACER SMOS  
PROCESS FOR FORMING N-  
TYPE TRANSISTORS  
Appl. No.: 10/619,877  
Filing Date: 07/15/2003  
Examiner: Christy L. Novacek  
Art Unit: 2822

<b>CERTIFICATE OF EXPRESS MAILING</b>	
I hereby certify that this correspondence is being deposited with the United States Postal Service's "Express Mail Post Office To Addressee" service under 37 C.F.R. § 1.10 on the date indicated below and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
EV 505576442 US	11/22/04
(Express Mail Label Number)	(Date of Deposit)
Robert A. Cooper	
(Printed Name)	
	
(Signature)	

**DECLARATION UNDER 37 C.F.R. § 1.131**

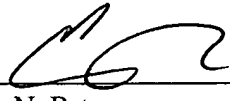
Commissioner for Patents  
PO Box 1450  
Alexandria, Virginia 22313-1450


Sir:

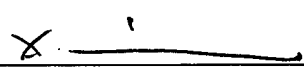
We, Eric N. Paton, Haihong Wang, and Qi Xiang, state and declare that:

1. Each of us is an inventor of at least one of Claims 1-20 currently pending in U.S. Patent Application No. 10/619,877 (hereinafter "the '877 application").
2. We understand that in an Office Action dated September 23, 2004, Claims 1-4, 7-10, and 17-20 were rejected as being unpatentable based in part on the use of U.S. Patent No. 6,762,085 to Zheng et al., entitled "METHOD OF FORMING A HIGH PERFORMANCE AND LOW COST CMOS DEVICE" (hereinafter "Zheng et al.").
3. We understand based on the information provided on the front page of Zheng et al. that Zheng et al. has a filing date of October 1, 2002.
4. At least by June 28, 2002, we conceived in the United States the ideas set forth in Claims 1-20 of the '877 application. Such conception is evidenced by the attached invention disclosure form pertaining to the subject matter of the present application, and which is dated June 28, 2002.
5. Based on the conception of the ideas set forth in Claims 1-20 at least by June 28, 2002, the subject matter recited in Claims 1-20 was invented by us prior to the October 1, 2002 filing date of Zheng et al.

6. We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are true, and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the patent application or any patent issuing therefrom.

Date: 11/18/04 By:   
Eric N. Paton

Date: 11/18/2004 By:   
Haihong Wang

Date: 11/17/04 By:   
Qi Xiang

Friday, June 28, 2002

SMOS Patent Harvesting Session, Group 4:

Technical Leader: Qi Xiang

# AMD INVENTION DISCLOSURE

TLD ID#

10970

Rec'd date

PRIORITY CODE

A B X

C D

California & Asia: x42110, return to MS68;

Texas: x55964 return to MS562;

Dresden & Europe: x83401 Silke Kretzschmar at MS E21-PP.

This invention applies to: Project: ☐ Product: ☐ Process: ☐ Technology: ☐ Other: ☐

IMPORTANT Please identify any potential use: \_\_\_\_\_

List 2 to 5 key search words related to the invention: \_\_\_\_\_

Working title of invention: Offset spacer for NMOS As Extension  
implant to compensate for As enhanced diffusion

Inventor's signature: Eric Paton date: 6/28/02

Inventor's printed full name: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Employee #: \_\_\_\_\_ Extension: \_\_\_\_\_ Mail stop: \_\_\_\_\_ Home telephone: ( ) \_\_\_\_\_

AMD email address: \_\_\_\_\_ AMD office FAX: ( ) \_\_\_\_\_

Division: \_\_\_\_\_ Directorate: \_\_\_\_\_ Dept #: \_\_\_\_\_ Dept : \_\_\_\_\_ Manager: \_\_\_\_\_

Residence address: \_\_\_\_\_

Post Office address: \_\_\_\_\_

Co-Inventor's signature: Hai Hong Wang date: \_\_\_\_\_

Co-Inventor's printed full name: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Employee #: \_\_\_\_\_ Extension: \_\_\_\_\_ Mail stop: \_\_\_\_\_ Home telephone: ( ) \_\_\_\_\_

AMD email address: \_\_\_\_\_ AMD office FAX: ( ) \_\_\_\_\_

Division: \_\_\_\_\_ Directorate: \_\_\_\_\_ Dept #: \_\_\_\_\_ Dept : \_\_\_\_\_ Manager: \_\_\_\_\_

Residence address: \_\_\_\_\_

Post Office address: \_\_\_\_\_

Co-Inventor's signature: Qi Xiang date: \_\_\_\_\_

Co-Inventor's printed full name: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Employee #: \_\_\_\_\_ Extension: \_\_\_\_\_ Mail stop: \_\_\_\_\_ Home telephone: ( ) \_\_\_\_\_

AMD email address: \_\_\_\_\_ AMD office FAX: ( ) \_\_\_\_\_

Division: \_\_\_\_\_ Directorate: \_\_\_\_\_ Dept #: \_\_\_\_\_ Dept : \_\_\_\_\_ Manager: \_\_\_\_\_

Residence address: \_\_\_\_\_

Post Office address: \_\_\_\_\_

Co-Inventor's signature: \_\_\_\_\_ date: \_\_\_\_\_

Co-Inventor's printed full name: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Employee #: \_\_\_\_\_ Extension: \_\_\_\_\_ Mail stop: \_\_\_\_\_ Home telephone: ( ) \_\_\_\_\_

AMD email address: \_\_\_\_\_ AMD office FAX: ( ) \_\_\_\_\_

Division: \_\_\_\_\_ Directorate: \_\_\_\_\_ Dept #: \_\_\_\_\_ Dept : \_\_\_\_\_ Manager: \_\_\_\_\_

Residence address: \_\_\_\_\_

Post Office address: \_\_\_\_\_

State total number of inventors here: \_\_\_\_\_. If there are more than four inventors, insert duplicate page 1.

HARVESTING LAW FIRM ATTORNEYS: FOLEY & LARDNER

Joe Ziebert, Ron Coslick

Witness 1 initial: \_\_\_\_\_ Witness 2 initial: \_\_\_\_\_

Patent Harvesting Breakout Session, Group 4: SMOS  
Friday, June 28, 2002  
Technical Leader: Qi Xiang

Participant Addresses  
(Please verify all information and fill in any blank areas)

FULL NAME & EMAIL	CITIZENS HIP	EMPL#	DEPT#	M/S	WORK#	FAX#	ADDRESS	CITY	STATE	ZIP CODE
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Paton, Eric N ERIC.PATON@AMD.COM	USA	024643	07195	49	408/749- 2944	408/774- 8923	498 Rio Grande Ct	Morgan Hill	CA	95037
Wang, Hailong HATHONG-WANG@AMD.COM	China	025468	07360	143	408/749- 3771		34170 Donahue Terr	Fremont	CA	94555
Xiang, Qi QI-XIANG@AMD.COM	China	024395	07360	143	408/749- 4771	408/749- 5585	1119 Thames Dr	San Jose	CA	95129

Friday, June 28, 2002

SMOS Patent Harvesting Session, Group 4:

Technical Leader: Qi Xiang

# AMD INVENTION DISCLOSURE

TLD ID#

Rec'd date

California & Asia: x42110, return to MS68;

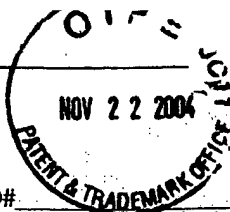
Texas: x55964 return to MS562;

Dresden & Europe: x83401 Silke Kretschmar at MS E21-PP.

PRIORITY CODE

A \_\_\_\_\_ B \_\_\_\_\_

C \_\_\_\_\_ D \_\_\_\_\_



Identify known relevant art (patents, publications, other information):

Offset spacer is used for Boron in current Si devices without side offset spacer for Boron with be applied in this invention to Arsenic.

State the problem solved by the invention:

compensate for the enhanced lateral diffusion of Arsenic under the gate edge. Too much overlap of the source/drain and the channel, will result in short channel effects.

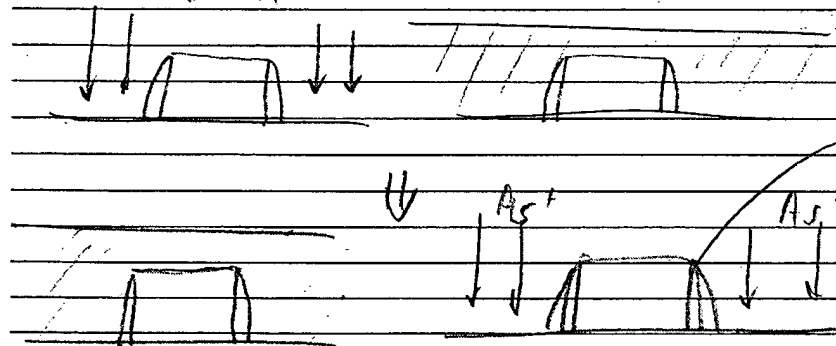
Brief description and sketch of the invention (please attach copies of documents like AMD patent notebook pages, reports and drawings that are helpful in describing / understanding the invention):

Suppressed Boron diffusion will prevent sufficient overlap of the gate and source/drain, resulting in too low of a drive current ( $I_{dsat}$ ).

PMOS  
Boron

NMOS

Second zero spacer for NMOS device only.



Patent notebook # \_\_\_\_\_ Page numbers \_\_\_\_\_ Number of drawings \_\_\_\_\_

HARVESTING LAW FIRM/ATTORNEYS: FOLEY & LARDNER

Joe Ziebert, Ron Coslick

Witness 1 initial: \_\_\_\_\_ Witness 2 initial: \_\_\_\_\_

Friday, June 28, 2002

SMOS Patent Harvesting Session, Group 4:

Technical Leader: Qi Xiang

## AMD INVENTION DISCLOSURE

NOV 22 2004

PATENT & TRADEMARK

PRIORITY CODE

A \_\_\_\_\_ B \_\_\_\_\_

C \_\_\_\_\_ D \_\_\_\_\_

TLD ID# \_\_\_\_\_

Rec'd date \_\_\_\_\_

California & Asia: x42110, return to MS68;

Texas: x55964 return to MS562;

Dresden & Europe: x83401 Silke Kretzschmar at MS E21-PP.

Advantages (check all that apply):

<input type="checkbox"/> simplifies manufacturing	<input type="checkbox"/> improves accuracy / precision	<input type="checkbox"/> reduces component parts
<input type="checkbox"/> reduces cost of manufacturing	<input type="checkbox"/> improves reliability	<input type="checkbox"/> improves signal to noise ratio
<input type="checkbox"/> improves density	<input type="checkbox"/> improves efficiency	<input type="checkbox"/> provides new functionality
<input type="checkbox"/> increases operating speed	<input type="checkbox"/> increases operating range	<input type="checkbox"/> other, explain below

Discussion of advantage(s) of the invention over other solutions

(emphasize technical advance in the art as measured against known art): the procedure  
is well established on current devices because Boron  
diffuses faster than Arsenic in Si devices.

Please take special care to preserve documentary evidence of the original date of conception of the invention. AMD Inventors' notebooks with witness signatures are useful in this regard. Notebooks are issued on request to inventors by the local AMD site Technical Librarian.

Please attach copy of first written description(s) of invention, with dates, names of persons with whom the description was discussed.

Please attach copy of first drawing(s) of invention, with date(s).

Describe any external disclosure of invention, place, date, circumstances of disclosure, with copy of NDA.

Does plan exist to publish, disclose or sell? No ☐, Yes ☐, If yes, where and when? \_\_\_\_\_

Was invention jointly developed with participation of inventors from outside AMD: No ☐, Yes ☐,

If yes, Company name \_\_\_\_\_,

If yes, name of AMD business contact and development contract no. \_\_\_\_\_

**I have read and understood this disclosure and read and signed each page of the attachments:**

**Witness 1**

signature: \_\_\_\_\_ Date: \_\_\_\_\_

Printed name: \_\_\_\_\_ Employee #: \_\_\_\_\_

**Witness 2**

signature: \_\_\_\_\_ Date: \_\_\_\_\_

Printed name: \_\_\_\_\_ Employee #: \_\_\_\_\_

Name(s) of attorney(s) preferred by inventor(s) to prepare patent application, if known: \_\_\_\_\_